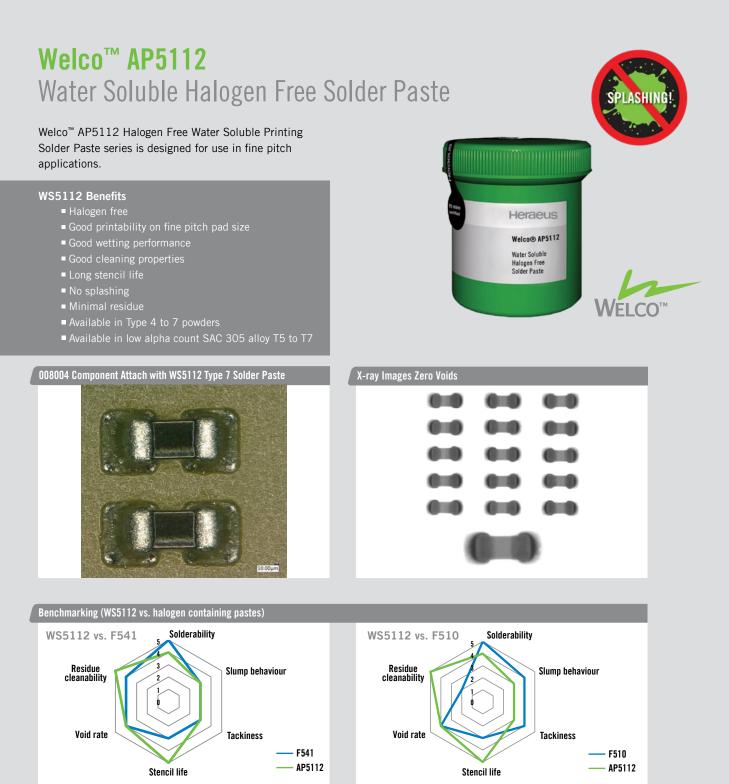
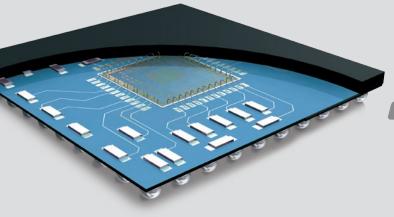
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Remark: $0 \longrightarrow 5$ (from worst to best)



Applications

System In Package	Die attach, components attach
Fine Pitch Assembly	Flipchip attach
Bumping	Wafer bumping, substrate bumping

Product Properties Table

Water Soluble Solder Paste – Overview	
Series	W\$5112
SIP (Die/Component attach)	+++
FC Attach/Wafer/Substrate bumping	+++
Application	
Print	+++
Properties	
Flux activity (J-STD-004)	H1
Halogen free	+++
Solderability	+++
Slump behavior	+++
Tackiness	+++
Stencil life	+++
Void rate	+++
Residue cleanability	+++
Powder compatibility (Type $3-4$)	+++
Powder compatibility (Type 5 - 7)	+++

Viscosity Changes Over Printing Time



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